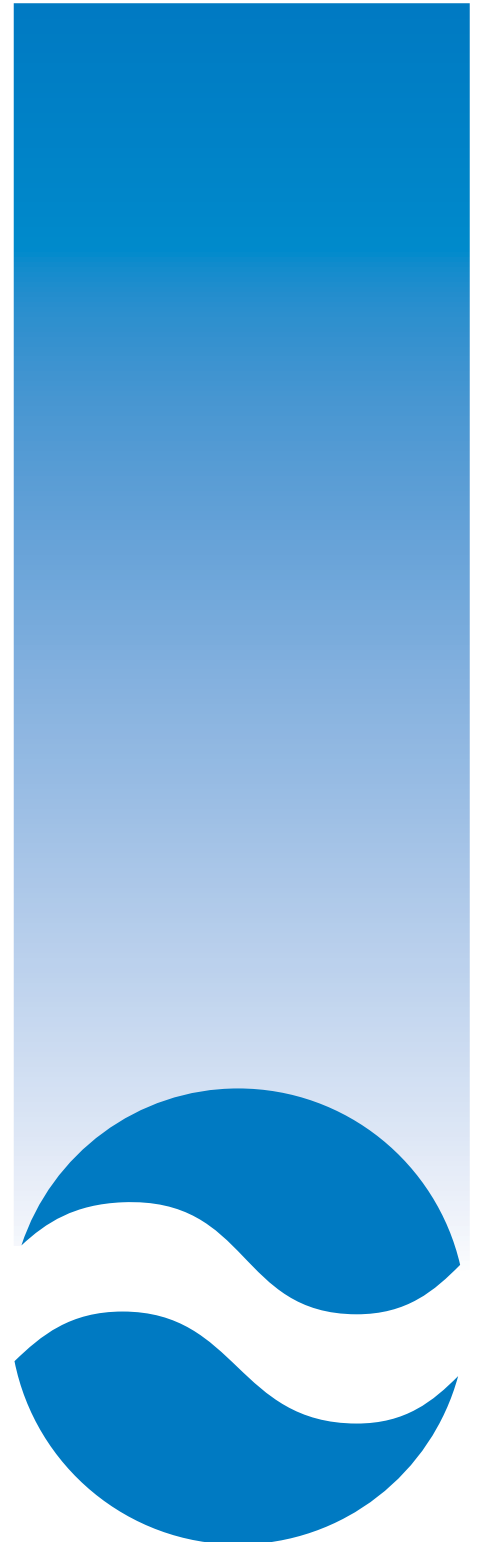


ECA/IPC/JEDEC J-STD-075

August 2008

JOINT INDUSTRY STANDARD

Classification of
Non-IC Electronic
Components for
Assembly
Processes



Documents

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Classification of Non-IC Electronic Components for Assembly Processes

A joint standard developed by the Electronic Components Association S-1 Passive Component Committees Steering Group, IPC Plastic Chip Carrier Cracking Task Group (B-10a) and the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices

Users of this standard are encouraged to participate in the development of future revisions.

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Acknowledgment

Members of the Electronic Components Association S-1 Passive Component Committees Steering Group, IPC Association Connecting Electronics Industries® IPC Plastic Chip Carrier Cracking Task Group (B-10a) and the JEDEC Solid State Technology Association JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices have worked together to develop this document. We would like to thank them for their dedication to this effort.

Any document involving a complex technology draws material from a vast number of sources. While the principal members of the Joint Moisture Classification Working Group are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the ECA, IPC and JEDEC extend their gratitude.

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